



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20170807000
Top-side symbol Font size change for OMAP3 CUS Devices
Information Only**

Date: August 07, 2017
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

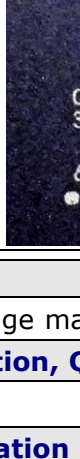
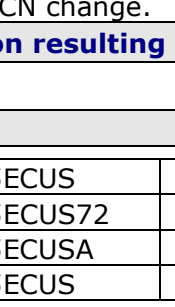
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Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OMAP3530ECUS72	null

Technical details of this Product Change follow on the next page(s).

Notification Number:	20170807000	Notification Date:	Aug 07, 2017
Title:	Top-side symbol Font size change for OMAP3 CUS Devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
The family of OMAP3 CUS devices will be marked with a slightly different font size as shown below.			
	From	To	
Logo size, mm	2.00	2.70	
Character height, mm	0.90	1.20	
Character height of "TM", mm	0.75	0.95	
Device Marking sample			
Reason for Change:			
To improve legibility on OMAP3 CUS package marking			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
None			
Anticipated impact on Material Declaration			
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.
Changes to product identification resulting from this notification:			
Top mark with new font size.			
Product Affected:			
3530ECUSAGRM	OMAP3515ECUS	OMAP3525ECUS72	OMAP3530ECUSA
OMAP3503ECUS	OMAP3515ECUS72	OMAP3525ECUSA	
OMAP3503ECUS72	OMAP3515ECUSA	OMAP3530ECUS	
OMAP3503ECUSA	OMAP3525ECUS	OMAP3530ECUS72	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com